IN THE CLAIMS:

Please AMEND claims 48-51, 53, 55, 57, 58 and 60-62, as follows.

1-47. (Cancelled)

48. (Currently Amended) An exposure apparatus for exposing a wafer to an exposure light via a pattern of a reticle, said apparatus comprising:

a chamber in which ~~an atmosphere is conditioned to be different from an atmosphere in another apparatus outside of said exposure apparatus and the wafer is exposed to the pattern, the atmosphere in said chamber being purged with an inert gas~~ the exposure light passes;

a conditioner configured to circulate a gas through said chamber and to purge an atmosphere in said chamber with an inert gas; and

a port ~~section~~ through which the wafer is transferred between said chamber and ~~the other~~ another apparatus outside of said exposure apparatus, said port ~~section~~ having a load-lock mechanism including ~~a vacuum mechanism for creating~~ a pump configured to create a vacuum below atmospheric pressure ~~inside of~~ in said port ~~section~~ and a supply mechanism ~~for supplying~~ configured to supply the inert gas ~~to the inside of~~ into said port ~~section~~.

49. (Currently Amended) An apparatus according to claim 48, wherein said exposure apparatus comprises a plurality of said ~~port sections~~ ports.

50. (Currently Amended) An apparatus according to claim 49, wherein said plurality of ~~port sections comprises~~ ports comprise a first port ~~section for loading~~ configured to load the wafer and a second port ~~section for unloading~~ configured to unload the wafer.

51. (Currently Amended) An apparatus according to claim 48, further comprising an interface section for stocking a wafer between said port ~~section~~ and the other apparatus.

52. (Previously Presented) An apparatus according to claim 51, wherein said interface section comprises a load-lock mechanism.

53. (Currently Amended) An apparatus according to claim 51, wherein said interface section is shared by a plurality of said ~~port sections~~ ports.

54. (Previously Presented) An apparatus according to claim 48, wherein the other apparatus includes a coating/developing system.

55. (Currently Amended) An apparatus according to claim 48, wherein said port ~~section~~ comprises a temperature control mechanism for controlling a temperature of the wafer.

56. (Previously Presented) An apparatus according to claim 55, wherein said temperature control mechanism comprises at least one of a heater and a cooler.

57. (Currently Amended) An apparatus according to claim 55, wherein said load-lock mechanism and said temperature control mechanism are configured to operate in parallel with each other.

58. (Previously Presented) An apparatus according to claim 48, wherein said chamber comprises a temperature control mechanism for controlling a temperature of the wafer.

59. (Cancelled)

60. (Currently Amended) A system for manufacturing a device, said system comprising:

an exposure apparatus as defined in claim 48, for exposing a wafer, in which the device is to be manufactured, to an exposure light via a pattern of a reticle; and

another apparatus ~~which performs,~~ configured to perform for the wafer, at least one of a pre-process and a post-process with respect to an exposure process performed by said exposure apparatus.

61. (Currently Amended) A method of manufacturing a device, said method comprising steps of:

exposing a wafer to an exposure light via a pattern of a reticle using an exposure apparatus as defined in claim 48; ~~and~~

developing the exposed wafer; and

processing the developed wafer to manufacture the device.

62. (Currently Amended) A method of manufacturing a device, said method comprising:

a first process step of processing a wafer using a system as defined in claim 60; and

a second process step of processing the wafer which has been processed in said first process step to manufacturing the device.